

**In the claims**

**Cancel claims 8-19 and 27-38.**

**Remaining claims are 1-7 and 20-26.**

1        1. A process for fabricating a thin-film magnetic head having an air bearing  
2        surface (ABS), the method comprising the unordered steps of:

- 3              (a) polishing the surface of a first side of a monolithic substrate wafer;  
4              (b) forming on the surface of the first side of the monolithic substrate wafer  
5        a first array of magnetic read head structures and magnetic write head structures each  
6        having a head gap;  
7              (c) polishing the surface of the other side of the monolithic substrate wafer;  
8              (d) forming on the surface of the other side of the monolithic substrate wafer  
9        a second array of magnetic read head structures and magnetic write head structures  
10      disposed such that a plurality of the magnetic read head gaps on one of the monolithic  
11      substrate surfaces are each aligned to form a read/write track-pair with a corresponding  
12      one of the magnetic write head gaps on the other monolithic substrate surface;  
13              (e) cutting the monolithic substrate to expose the head gaps of a plurality of  
14      read/write track-pairs; and  
15              (f) lapping the ABS to refine the depth of the exposed head gaps.

1        2. The method of claim 1 wherein the first and second arrays comprise:  
2        a plurality of magnetic read and write head structures disposed such that each  
3        read head structure is covered by a collocated write head structure in a piggy-back  
4        configuration.

1        3. The method of claim 2 wherein each of the magnetic read heads includes  
2        a magnetoresistive (MR) sensor element.

1        4. The method of claim 1 further comprising the step of:  
2              (h) cutting the monolithic substrate to separate therefrom a thin-film magnetic  
3        head having a single read/write track-pair.

1        5. The method of claim 4 wherein each of the magnetic read heads includes  
2        a magnetoresistive (MR) sensor element.

1           6.     The method of claim 1 wherein the first array comprises a plurality of  
2           magnetic read head structures adjoining one another and the second array comprises a  
3           plurality of magnetic write head structures adjoining one another.

1           7.     The method of claim 1 wherein each of the magnetic read heads includes  
2           a magnetoresistive (MR) sensor element.

- 8.       (Canceled)
- 9.       (Canceled)
- 10.      (Canceled)
- 11.      (Canceled)
- 12.      (Canceled)
- 13.      (Canceled)
- 14.      (Canceled)
- 15.      (Canceled)
- 16.      (Canceled)
- 17.      (Canceled)
- 18.      (Canceled)
- 19.      (Canceled)

1           20.    A process for fabricating a thin-film magnetic head having an air bearing  
2           surface (ABS), the method comprising the unordered steps of:

- 3           (a)    polishing the surface of a front side of a monolithic substrate wafer;
- 4           (b)    forming on the surface of the front side of the monolithic substrate wafer  
5           an array of magnetic read head structures and magnetic write head structures each having  
6           a head gap;
- 7           (c)    sectioning the monolithic substrate wafer to form a plurality of wafer  
8           subsections each having a back surface;
- 9           (d)    fixing the back surfaces of a pair of the wafer subsections to one another  
10          disposed such that a plurality of the magnetic read head gaps on the front surface of one  
11          of the wafer subsections are each aligned to form a read/write track-pair with a  
12          corresponding one of the magnetic write head gaps on the front surface of the other wafer  
13          subsection;
- 14          (e)    cutting the fixed pair of wafer subsections to expose the head gaps of a  
15          plurality of read/write track-pairs; and
- 16          (f)    lapping the ABS to refine the depth of the exposed head gaps.

1           **21.**   The method of claim 20 wherein the first and second arrays comprise:  
2                 a plurality of magnetic read and write head structures disposed such that each  
3                 read head structure is covered by a collocated write head structure in a piggy-back  
4                 configuration.

1           **22.**   The method of claim 21 wherein each of the magnetic read heads includes  
2                 a magnetoresistive (MR) sensor element.

1           **23.**   The method of claim 20 further comprising the step of:  
2                 (h)   cutting the fixed pair of wafer subsections to separate therefrom a  
3                 thin-film magnetic head having a single read/write track-pair.

1           **24.**   The method of claim 23 wherein each of the magnetic read heads includes  
2                 a magnetoresistive (MR) sensor element.

1           **25.**   The method of claim 20 wherein the array comprises a plurality of  
2                 magnetic read head structures adjoining one another.

1           **26.**   The method of claim 20 wherein each of the magnetic read heads includes  
2                 a magnetoresistive (MR) sensor element.

- 27.**   (Canceled)
- 28.**   (Canceled)
- 29.**   (Canceled)
- 30.**   (Canceled)
- 31.**   (Canceled)
- 32.**   (Canceled)
- 33.**   (Canceled)
- 34.**   (Canceled)
- 35.**   (Canceled)
- 36.**   (Canceled)
- 37.**   (Canceled)
- 38.**   (Canceled)

**In the abstract**

Page 20, lines 1 and 2 amend the title from ~~A MONOLITHIC MAGNETIC READ WHILE- WRITE HEAD APPARATUS AND METHOD OF MANUFACTURE~~ to METHOD OF MAKING A MONOLITHIC MAGNETIC READ WHILE-WRITE HEAD APPARATUS.